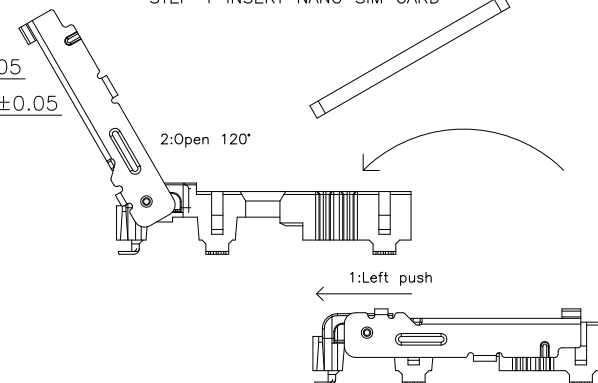


REV.	ECN.NO.	MODIFY.CONTENT
A		NEW

NOTES:

-  PAD AREA
-  OTHER COMPONENT KEEPOUT AREA
-  VIP AND TRACE KEEPOUT AREA
STAND OFF AREA (禁止摆件)
-  GND ONLY

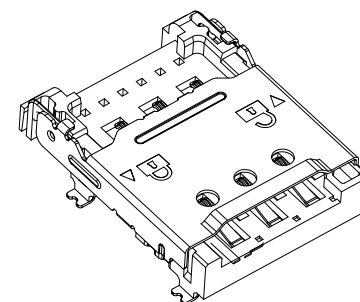
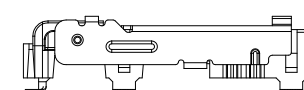
STEP 1 INSERT NANO SIM CARD



STEP 2 PUSH THE SHELL



STEP 3 FINISH

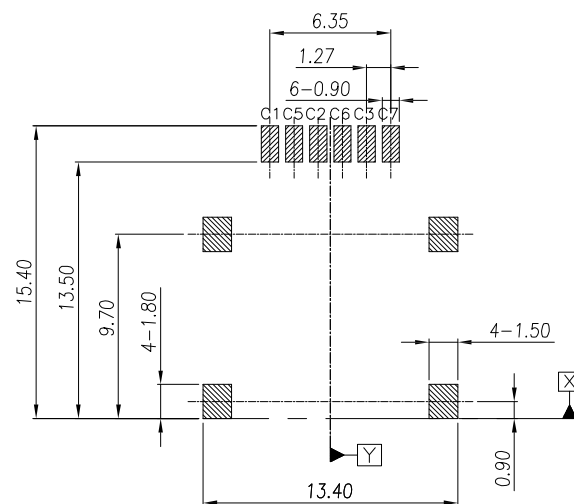
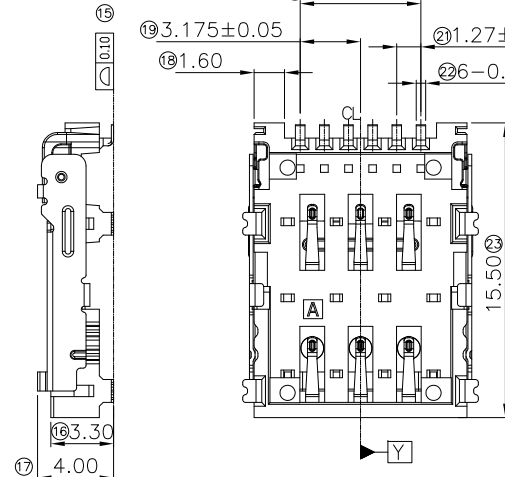
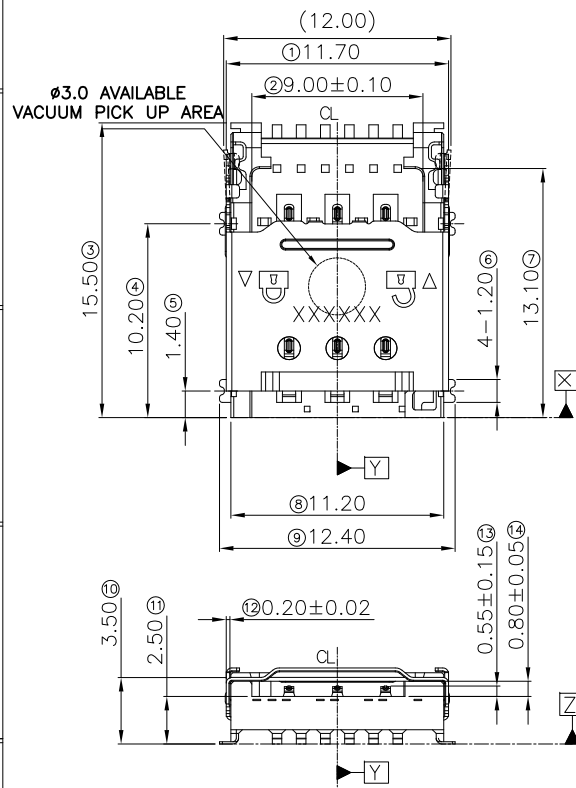


NOTES:

- MATERIAL:
 - 1.1) PLASTIC:LCP BLACK
 - 1.2) TERMINAL:C5210,T=0.15±0.02
 - 1.3) SHELL:MATERIAL:SUS304,T=0.20±0.02
- TERMINAL PLATING:
 - 2-1:TERMINAL: CONTACT AREA:GOLD PLATING
SOLDER AREA:GOLD FLASH
UNDER PLATING:NICKEL 50u" Min.
 - 2-2:SHELL: NO PLATING
- PART MUST COMPLY TAI SOL HF WD-3-I-091 SPECIFICATION

PART.NO.:
SP204-AP401-**-**

- 08: 功能区镀金1U ", 锡脚Gold Flash
- 09: 功能区镀金3U ", 锡脚Gold Flash
- 10: 功能区镀金5U ", 锡脚Gold Flash
- 11: 功能区镀金15U ", 锡脚Gold Flash
- 12: 功能区镀金30U ", 锡脚Gold Flash



RECOMMENDED PCB LAYOUT
TOLERANCE ±0.05
 SMT SOLDER AREA

PIN NO.	PIN NAME	PIN TYPE
C1	VCC	Power
C2	RST	
C3	CLK	
C5	GND	Power
C6	VPP	
C7	I/O	Bidirectional

GENERAL TOLERANCE		DWG.NO.	SP204-AN401-00	PART.NO.	SP204-AN401-**-**	DRAWN	YUAN 2021.07.09	UNIT	mm	SCALE	1:1
x.±0.50	x.*± 5°	REV.	A	TITLE	Nano SIM H4.0掀盖式	CHECKED		 东莞市欧联电子科技有限公司 DONGGUAN OLN ELECTRONICS TECHNOLOGY CO., LTD.			
.x±0.25	.x*± 2°	SIZE		SHEET	1 OF 2	APPROVED					
.xx±0.15	.xx± 1°	A4									